

■ General Description

The AME8903 is CMOS LDO regulator sourcing 500mA output current. The input voltage is as low as 1.4V and the output voltage can be set from 0.8V. The device consume 40μA of quiescent current (no load).

EN pin input logic level to control ON/OFF of the output voltage. The features low noise, high PSRR and good line/load transient. The device support protection such as over-load, short circuit and overheating.

■ Application

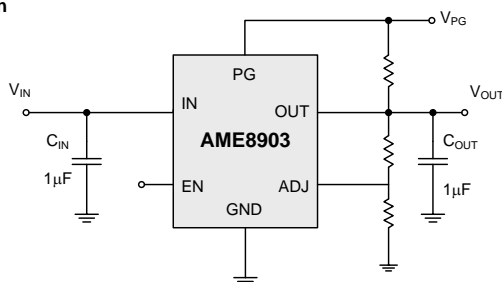
- Laptop, AIO, Mini PC
- Battery Powered Equipment
- Portable Communication Equipment
- Cameras, Image Sensors and Camcorders

■ Features

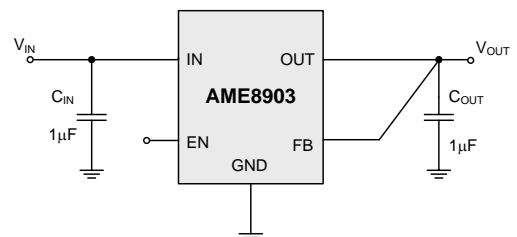
- Operating Input Voltage: 1.4V to 5.5V
- Adjustable Output Voltage: 0.8V to 5V
- Fixed Output Voltage: 0.8V to 4.5V(0.1V steps)
- Quiescent Current: 40μA(typ.)
- Low Dropout : 120mV(typ.) @0.5A, $V_{OUT} = 2.5V$
- Output Voltage Accuracy : $\pm 0.8\%$ ($V_{OUT} > 1.8V$)
- Stable with Small 1μF Ceramic Capacitors
- Over-Current Protection
- Thermal Shutdown Protection : 160°C
- Auto Output Discharge Function
- Available in SOT-25 & DFN-6G(1.2x1.2x0.37mm) & DFN-6D(2x2x0.75mm) Packages
- RoHS, Halogen Free and TSCA Compliance

■ Typical Application Schematic

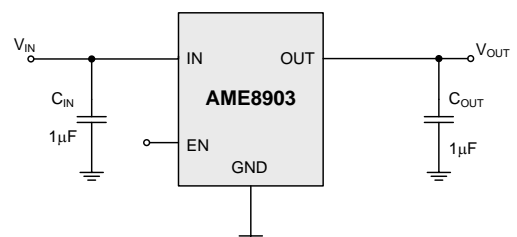
ADJ Version



Fix Version- with V_{FB}

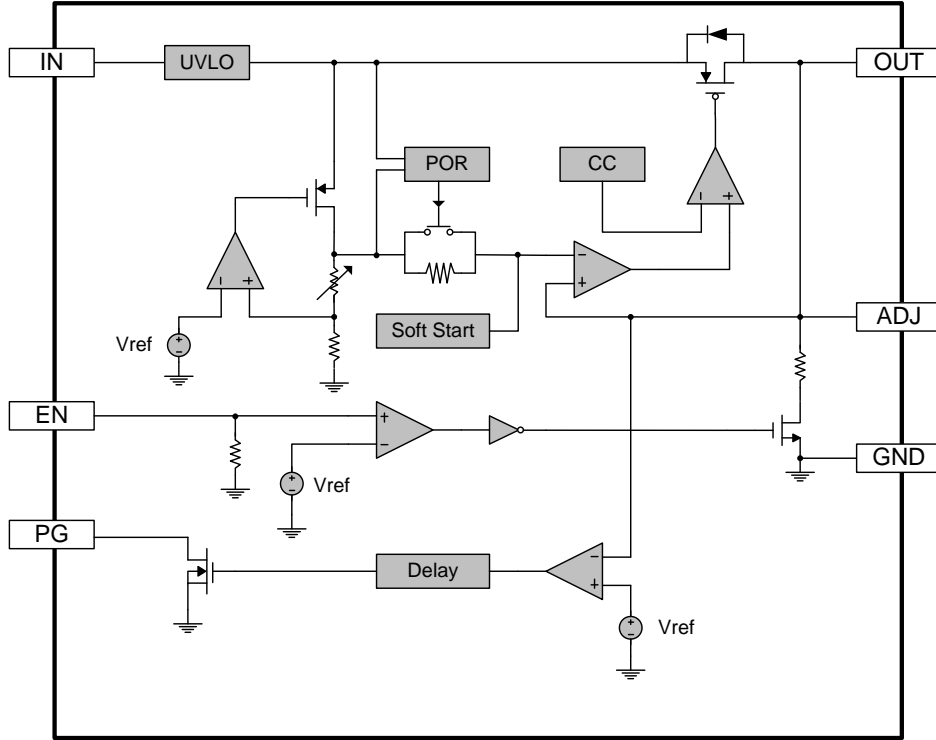


Fix Version – without V_{FB}

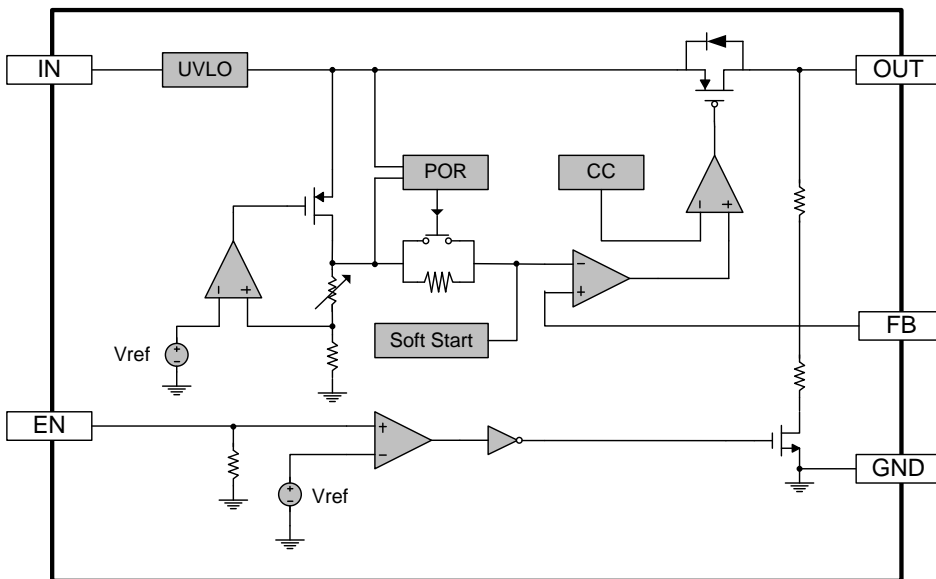


■ **Function Block Diagram**

ADJ Version

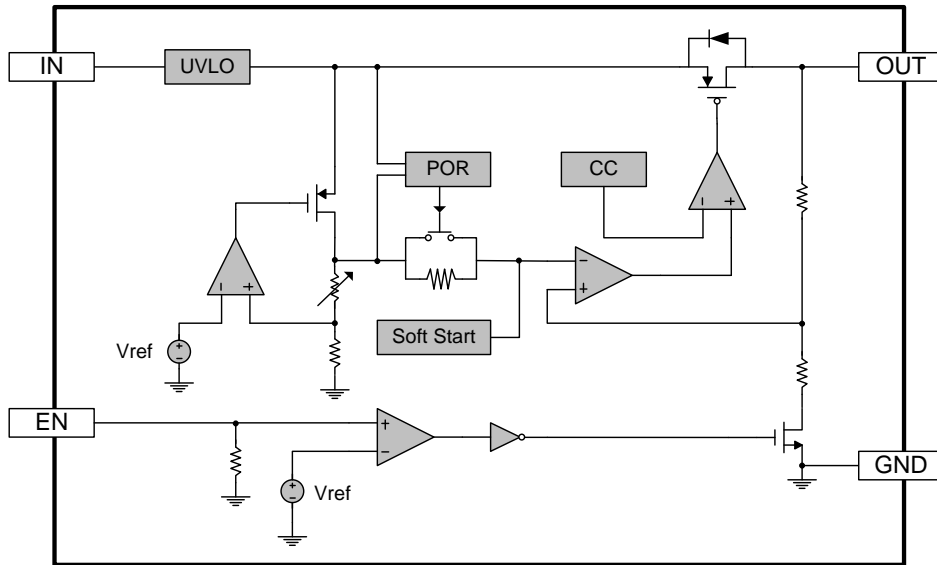


Fix Version – with V_{FB}

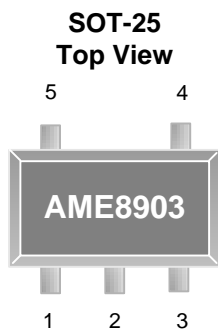


■ **Function Block Diagram (Contd.)**

Fix Version – without V_{FB}

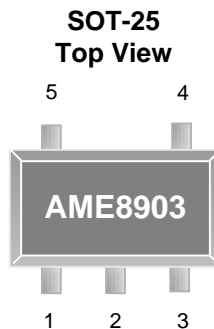


■ Pin Configuration



AME8903-AEVxxx

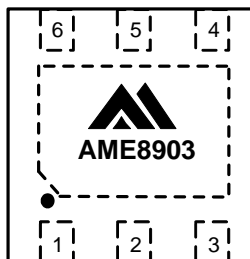
1. IN
2. GND
3. EN
4. NC
5. OUT



AME8903-DEVADJ

1. IN
2. GND
3. EN
4. ADJ
5. OUT

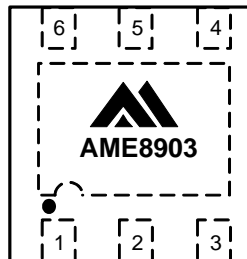
**DFN-6G
(1.2x1.2x0.37mm)
Top View**



AME8903-AVYxxx

1. OUT
2. FB
3. GND
4. EN
5. NC
6. IN

**DFN-6D
(2x2x0.75mm)
Top View**

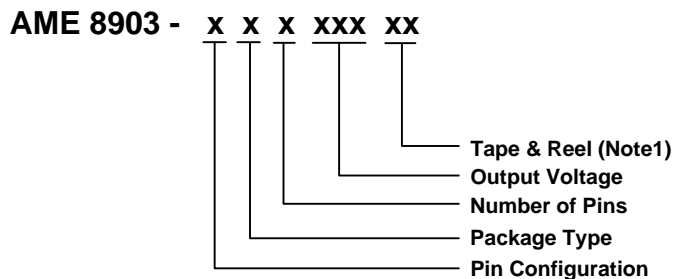


AME8903-DVYADJ

1. OUT
2. ADJ
3. GND
4. EN
5. PG
6. IN

■ Pin Description

| Pin Number | | | | I/O | Pin Name | Pin Description |
|------------|----|--------|--------|-----|----------|---|
| SOT-25 | | DFN-6G | DFN-6D | | | |
| A | D | A | D | | | |
| 5 | 5 | 1 | 1 | O | OUT | LDO Output pin |
| NA | 4 | 2 | 2 | I | ADJ/FB | Feedback Input pin |
| 2 | 2 | 3 | 3 | NA | GND | Ground pin |
| 3 | 3 | 4 | 4 | I | EN | Chip Enable Input pin (Active High) |
| 4 | NA | 5 | NA | NA | NC | Not Internally Connected. |
| 1 | 1 | 6 | 6 | I | IN | Power Supply Input pin |
| NA | NA | NA | 5 | O | PG | Power Good pin |
| NA | NA | EPAD | EPAD | NA | EPAD | Recommend to connect the EPAD to GND, but leaving it open is also acceptable. |

■ Ordering Information


| Pin Configuration | | Package Type | Number of Pins | Output Voltage |
|-------------------|--------|--------------|----------------|----------------|
| A (SOT-25) | 1. IN | E: SOT-2X | V: 5 | 100: 1.0V |
| | 2. GND | V: DFN | Y: 6 | 120: 1.2V |
| | 3. EN | | | 180: 1.8V |
| | 4. NC | | | 280: 2.8V |
| | 5. OUT | | | 300: 3.0V |
| D (SOT-25) | 1. IN | | | 330: 3.3V |
| | 2. GND | | | ADJ: ADJ |
| | 3. EN | | | |
| | 4. ADJ | | | |
| | 5. OUT | | | |
| A (DFN-6G) | 1. OUT | | | |
| | 2. FB | | | |
| | 3. GND | | | |
| | 4. EN | | | |
| | 5. NC | | | |
| | 6. IN | | | |
| D (DFN-6D) | 1. OUT | | | |
| | 2. ADJ | | | |
| | 3. GND | | | |
| | 4. EN | | | |
| | 5. PG | | | |
| | 6. IN | | | |

Note1: For DFN package only, please refer to AME8903 Available Option or consult AME sales office or authorized Rep. / Distributor for detail information.

■ Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit |
|--------------------|-----------|------------|------|
| Input Voltage | V_{IN} | -0.3 to +6 | V |
| Output Voltage | V_{OUT} | -0.3 to +6 | |
| Enable Voltage | V_{EN} | -0.3 to +6 | |
| FB/ADJ Pin | | -0.3 to +6 | |
| Power Good Pin | | -0.3 to +6 | |
| ESD Classification | HBM | ± 4000 | V |
| | MM | ± 200 | |
| | CDM | ± 1000 | |

■ Recommended Operation Conditions

| Parameter | Symbol | Value | Unit |
|----------------------------|-----------|-------------|------|
| Input Voltage Range | V_{IN} | 1.4 to 5.5 | V |
| Fix OUTPUT Voltage Range | V_{OUT} | 0.8 to 4.5 | |
| ADJ OUTPUT Voltage Range | V_{OUT} | 0.8 to 5 | |
| Ambient Temperature Range | T_A | -40 to +85 | °C |
| Junction Temperature Range | T_J | -40 to +125 | |
| Storage Temperature | T_{STG} | -55 to +150 | |

■ Thermal Information

| Parameter | Package | Die Attach | Symbol | Maximum | Unit |
|---|---------|----------------------|---------------|---------|--------|
| Thermal Resistance* (Junction to Case) | SOT-25 | Conductive Epoxy | θ_{JC} | 81 | °C / W |
| | DFN-6D | | | 16 | |
| | DFN-6G | Non-Conductive Epoxy | | 68 | |
| Thermal Resistance (Junction to Ambient) | SOT-25 | Conductive Epoxy | θ_{JA} | 260 | |
| | DFN-6D | | | 66 | |
| | DFN-6G | Non-Conductive Epoxy | | 167 | |
| Internal Power Dissipation | SOT-25 | Conductive Epoxy | P_D | 400 | mW |
| | DFN-6D | | | 1515 | |
| | DFN-6G | Non-Conductive Epoxy | | 600 | |
| Lead Temperature (soldering 10 sec)** | | | | 300 | °C |

* Measure θ_{JC} on backside center of Exposed Pad.

** MIL-STD-202G210F

■ Electrical Specifications
 $V_{IN} = V_{OUT-NOM} + 0.5V$ and $V_{IN} > 1.6V$, $V_{EN} = 1.2V$, $I_{OUT} = 1mA$, $C_{IN} = C_{OUT} = 1.0\mu F$, $T_J = 25^\circ C$.

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units | |
|-------------------------------|---------------|--|-----------------------------|------|-------|----------|----|
| Output Voltage Accuracy | $V_{OUT-ACC}$ | $V_{OUT} \geq 2.5V$ | -1 | | 1 | % | |
| | | $2.5V > V_{OUT} \geq 1.8V$ | -0.8 | | 0.8 | | |
| | | $V_{OUT} < 1.8V$ | -20 | | 20 | mV | |
| ADJ Reference Voltage | V_{ADJ} | $I_{OUT} = 1mA$ | 0.792 | 0.8 | 0.808 | V | |
| Line Regulation | REG_{LINE} | $V_{IN} = V_{OUT-NOM} + 0.5V$ to $5.25V$, $V_{IN} \geq 1.4V$ | | 0.02 | 0.1 | %/V | |
| Load Regulation | REG_{LOAD} | $I_{OUT} = 1mA$ to $500mA$ | | 0.5 | 10 | mV | |
| Dropout Voltage | V_{DROP} | $I_{OUT} = 500mA$ | $V_{OUT} < 1.05V$ | | Note2 | | mV |
| | | | $1.05V \leq V_{OUT} < 1.2V$ | | 585 | 750 | |
| | | | $1.2V \leq V_{OUT} < 1.5V$ | | 420 | 570 | |
| | | | $1.5V \leq V_{OUT} < 1.8V$ | | 295 | 400 | |
| | | | $1.8V \leq V_{OUT} < 2.1V$ | | 200 | 275 | |
| | | | $2.1V \leq V_{OUT} < 2.5V$ | | 150 | 230 | |
| | | | $2.5V \leq V_{OUT} < 3.0V$ | | 120 | 190 | |
| | | | $3.0V \leq V_{OUT}$ | | 90 | 165 | |
| Quiescent Current | I_Q | $V_{EN} = V_{IN}$, $I_{OUT} = 0mA$ | | 40 | 75 | μA | |
| Shutdown Current | I_{SHDN} | $V_{EN} = 0V$ | | 0.05 | 1 | | |
| Output Current Limit | I_{LIM} | $V_{OUT} = 90\%$ of $V_{OUT-NOM}$ | 520 | | | mA | |
| Short Circuit Current | I_{SC} | $V_{OUT} = 0V$ | | 100 | | | |
| Enable High Level | V_{EN-HI} | $V_{IN} = 5V$ | 1 | | | V | |
| Enable Low Level | V_{EN-LO} | $V_{IN} = 5V$ | | | 0.4 | | |
| Enable Input Current | I_{EN} | $V_{EN} = V_{IN} = 5.5V$ | | 0.15 | 0.6 | μA | |
| Output Discharge Resistance | R_{DSG} | | | 60 | | Ω | |
| Power Supply Ripple Rejection | PSRR | $I_{OUT} = 30mA$, $f = 1KHz$ | | 75 | | dB | |
| | | $I_{OUT} = 30mA$, $f = 100KHz$ | | 60 | | | |
| | | $I_{OUT} = 30mA$, $f = 1MHz$ | | 50 | | | |
| | | $I_{OUT} = 30mA$, $f = 10MHz$ | | 50 | | | |

 Note2: For V_{OUT} below 1.05V, Dropout Voltage is the V_{IN-MIN} to Output Differential.

■ Electrical Specifications (Contd.)
 $V_{IN} = V_{OUT-NOM} + 0.5V$ and $V_{IN} > 1.6V$, $V_{EN} = 1.2V$, $I_{OUT} = 1mA$, $C_{IN} = C_{OUT} = 1.0\mu F$, $T_J = 25^\circ C$.

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|-----------------------------|--------|--------------------|-----|-----|-----|---------------|
| Output Noise | eN | f = 10Hz to 100KHz | | 36 | | μV_{RMS} |
| PG Threshold Voltage | | V_{OUT} Rising | | 90 | | % |
| PG Hysteresis | | V_{OUT} Falling | | 10 | | % |
| PG Low Voltage | | PG sinks 1mA | | 0.1 | 0.2 | V |
| PG Delay Time | | | | 1.1 | | ms |
| Over Temperature Shutdown | OTS | | | 160 | | $^\circ C$ |
| Over Temperature Hysteresis | OTH | | | 35 | | $^\circ C$ |

■ Application Information

Input Capacitor

Bypass capacitor is placed to improve AC performance and recommended from IN to GND due to low impedance path. It is recommended to be adopted for reliable performance over temperature range by the X7R or X5R capacitor. A 1 μ F or greater capacitor locates as close as possible to AME8903.

The ESR is not required but it is recommended to use a ceramic capacitor for its low ESR and ESL. A good input capacitor will ease the influence of input trace inductance and source resistance during load current changes.

Output Capacitor

It is required to fulfill both requirements for minimum amount of capacitance and ESR in all LDOs application by output capacitor. The LDO requires an output capacitor connected as close as possible to the output and ground pins.

The AME8903 specifically work with low ESR ceramic output capacitor in space-saving and performance consideration. The recommended capacitor value is 1 μ F, ceramic X7R or X5R type due to its low capacitance variations over the specified temperature range. The ESR of output capacitor relates to stability and the maximum ESR should be less than 0.5 Ω .

Larger output capacitance is able to reduce noise and enhance load transient response, stability, and PSRR. When selecting the capacitor the changes with temperature, DC bias and package size needs to be required. Especially for small package size capacitors such as 0201 the effective capacitance drops rapidly with the applied DC bias voltage. Only ceramic capacitors are recommended due to low ESR, the other types like tantalum capacitors are not.

Enable

Shutdown mode: If the EN pin voltage is < 0.4V, AME8903 is disabled and its pass transistor is turned off. The active discharge transistor is active so the output voltage is pulled to GND through typical 60 Ω resistor.

Operation mode: If the EN pin voltage is > 1.0V, AME8903 is enabled and regulates the output voltage. The active discharge transistor is turned off.

The EN pin has internal pull-down current source with value of 0.15 μ A typ. which assures the device is turned off when the EN pin is unconnected. In case when the EN function isn't required the EN pin should be tied directly to IN pin.

Output Current Limit

Output current is internally limited to a 520mA min. The LDO will source this current when the output voltage drops down from the nominal output voltage (test condition is $V_{OUT-NOM} - 100mV$). If the output voltage is shorted to ground, the short circuit protection will limit the output current to 100mA Typ. The current limit and short circuit protection will work properly over the whole temperature and input voltage ranges. There is no limitation for the short circuit duration.

Reverse Current

When $V_{OUT} > V_{IN}$, body diode of PMOS will be forward biased. In the case, extended reverse current condition can be anticipated and the device may require additional external protection.

Enable Turn-On Time

Defined as the time from EN assertion to the point where V_{OUT} will reach 98% of its nominal value. This time is dependent on various application conditions such as $V_{OUT-NOM}$, C_{OUT} and T_A .

Power Supply Rejection Ratio (PSRR)

The AME8903 features high PSRR. The PSRR at higher frequencies (in the range above 100 kHz) can be tuned by the selection of C_{OUT} capacitor and proper PCB layout. A simple LC filter could be added to the AME8903's IN pin for further PSRR improvement.

■ Application Information (Contd.)

Thermal Shutdown

This feature prevents overheating from damaging to IC due to application failure. When the LDO's die temperature exceeds the thermal shutdown threshold value, AME8903 is internally disabled. The AME8903 will remain in this state until the die temperature decreases by value called thermal shutdown hysteresis. Once the IC temperature falls this way the LDO is back enabled.

Power Dissipation (P_D)

P_D induced by voltage drop across PMOS and by the output current flowing through AME8903 needs to be dissipated out from the chip. The maximum power dissipation ($P_{D(MAX)}$) is dependent on the PCB layout, number of used Cu layers, Cu layers thickness and the ambient temperature.

The maximum power dissipation can be calculated by following equation:

$$P_{D(MAX)} = \frac{T_J - T_A}{\theta_{JA}} [W]$$

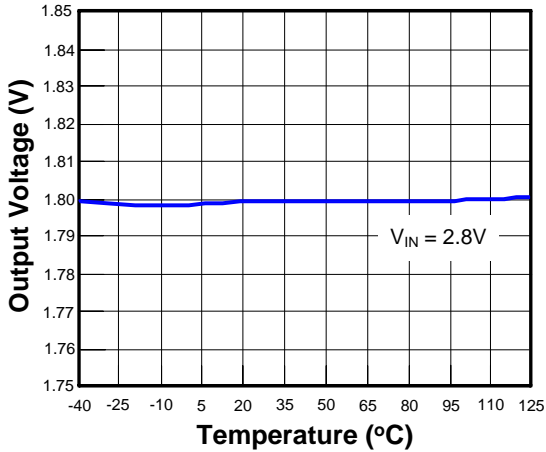
Where $(T_J - T_A)$ is the temperature difference between the junction and ambient temperatures and θ_{JA} is the thermal resistance (dependent on the PCB as mentioned above).

$$P_D = V_{IN} \cdot I_{GND} + (V_{IN} - V_{OUT}) \cdot I_{OUT} [W]$$

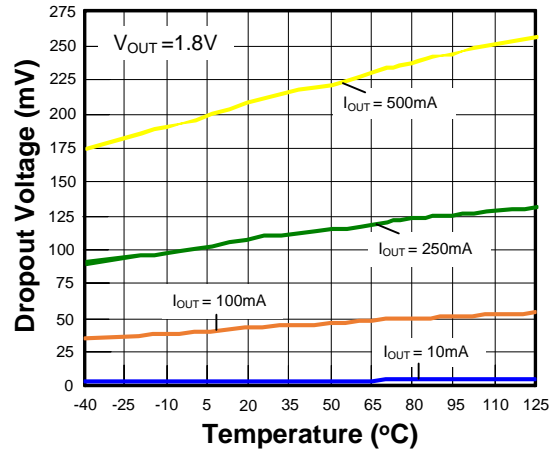
Where I_{GND} is the AME8903's ground current, which is dependent on the output load current. Connecting the exposed pad and N/C pin to a large ground planes helps to dissipate the heat from the chip.

■ **Characterization Curve**

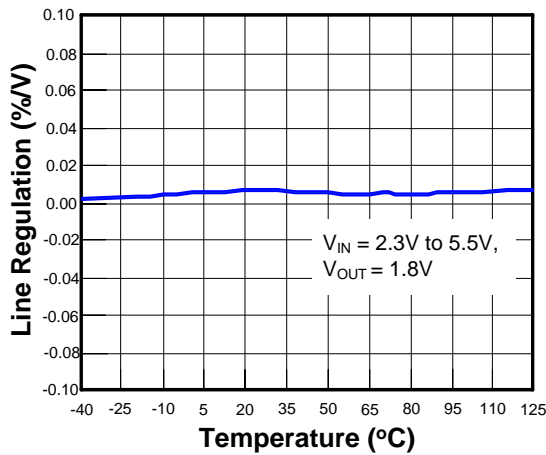
Output Voltage vs. Temp.



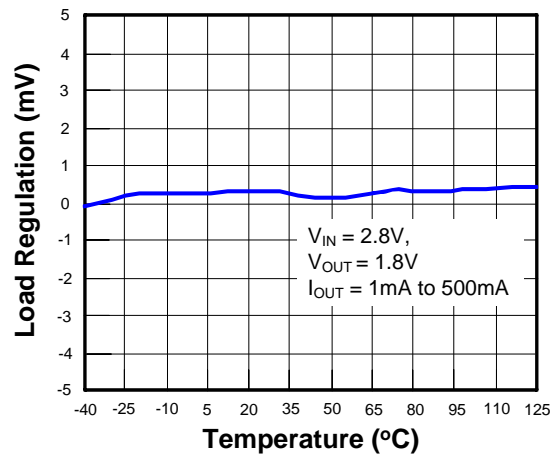
Dropout Voltage vs. Temp.



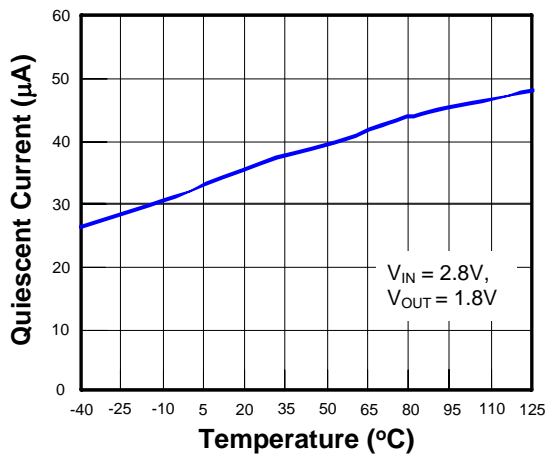
Line Regulation vs. Temp.



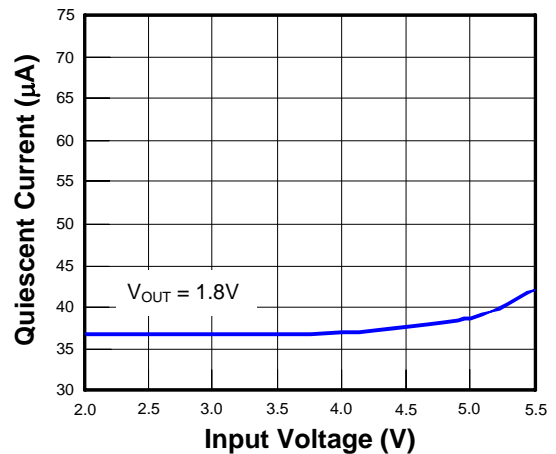
Load Regulation vs. Temp.



IQ vs. Temp.

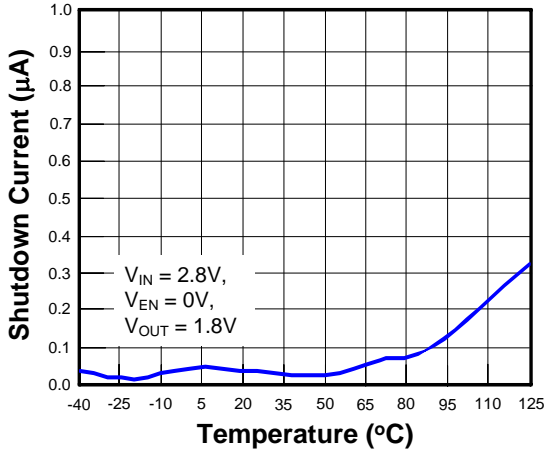


IQ vs. Input Voltage

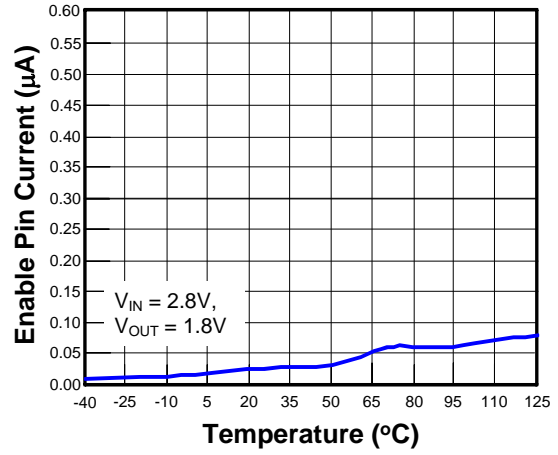


■ **Characterization Curve (Contd.)**

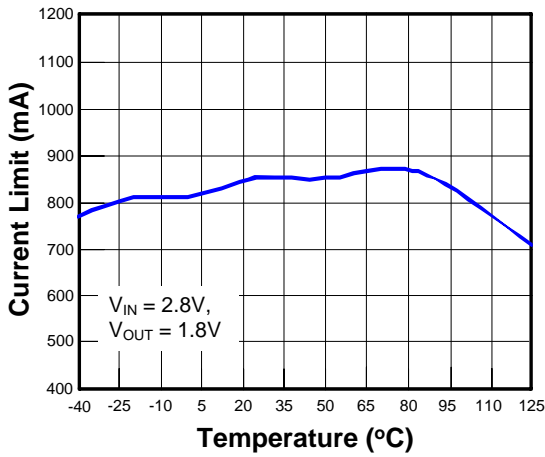
I_{SHDN} vs. Temp.



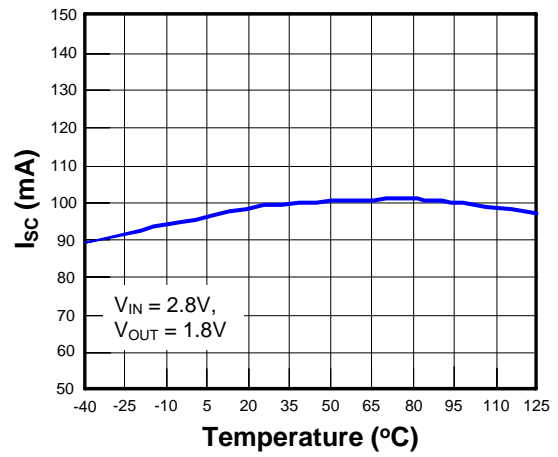
Enable Current vs. Temp.



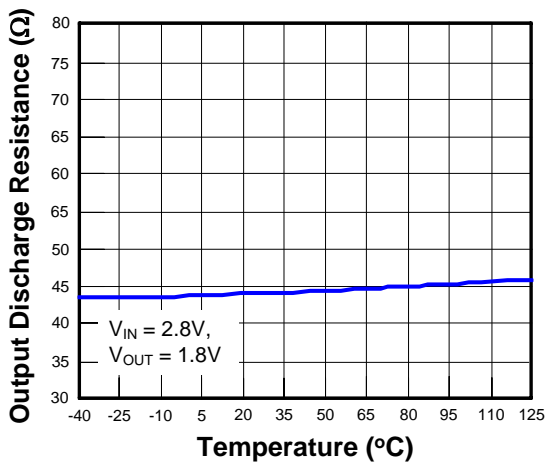
Current Limit vs. Temp.



Short Circuit Current vs. Temp.

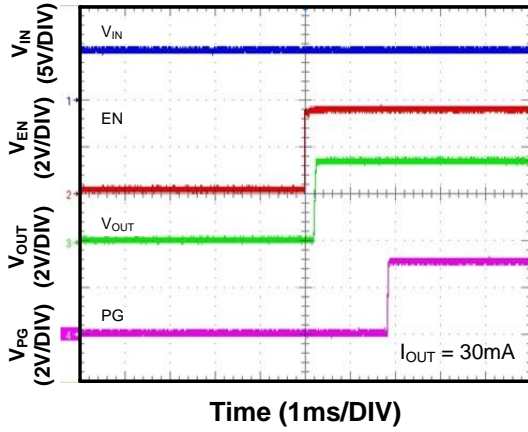


R_{DSG} vs. Temp.

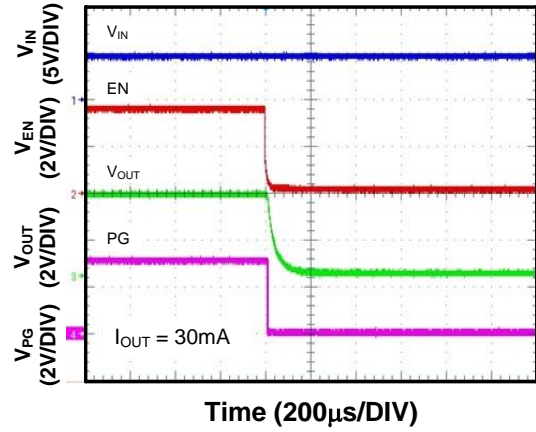


■ **Characterization Curve (Contd.)**

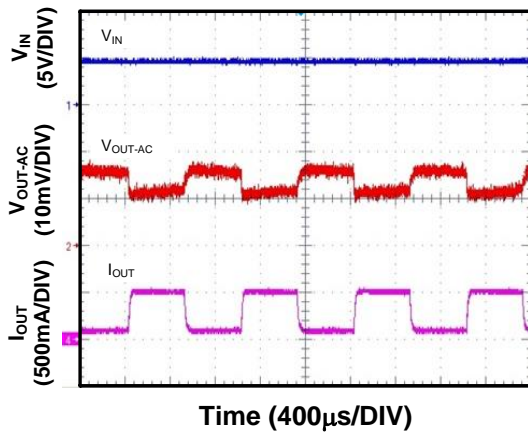
Start-Up from Enable



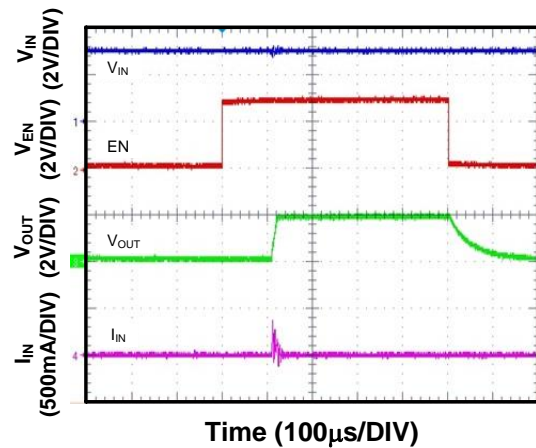
Shutdown from Disable



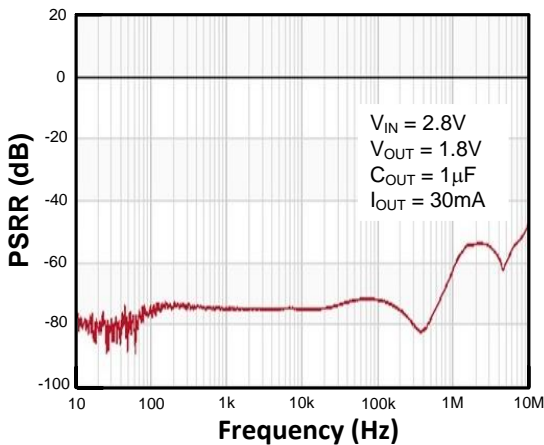
Load Transient Response



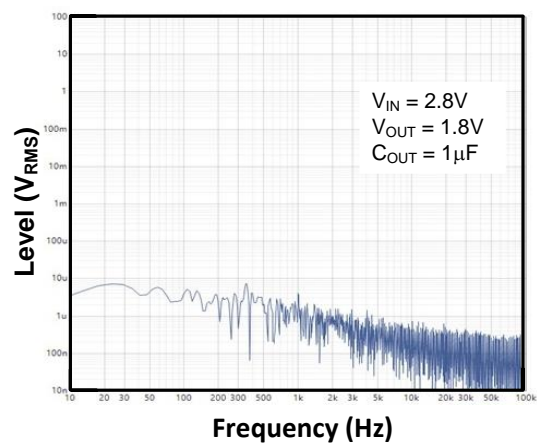
Turn-On/Off – EN Driven

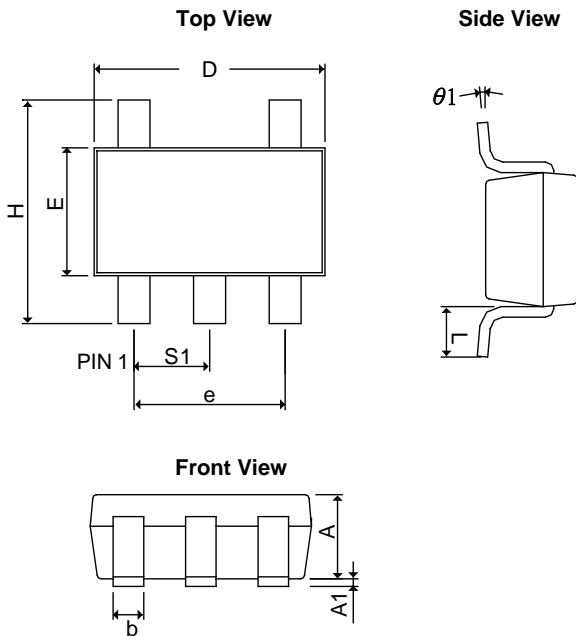


Power Supply Rejection Ratio

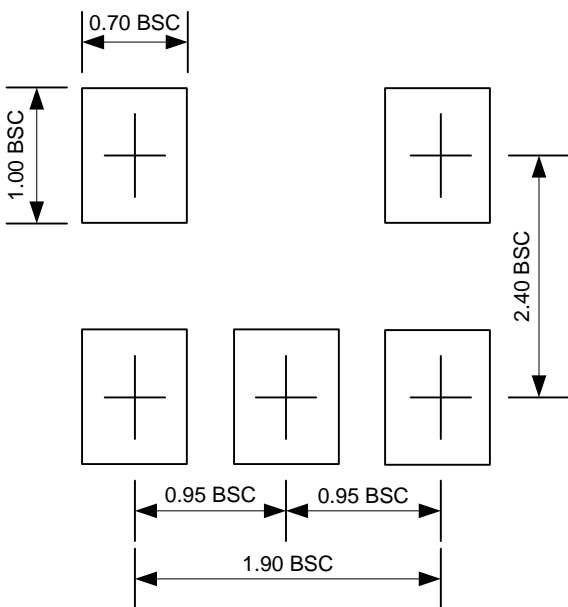


Output Voltage Noise Spectral

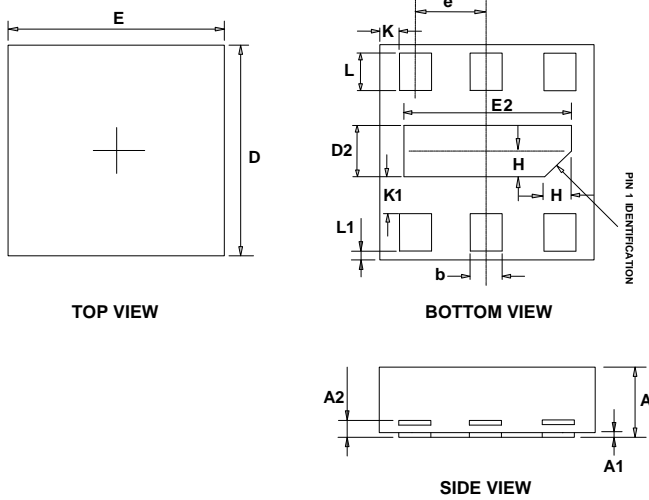


■ Package Dimension
SOT-25


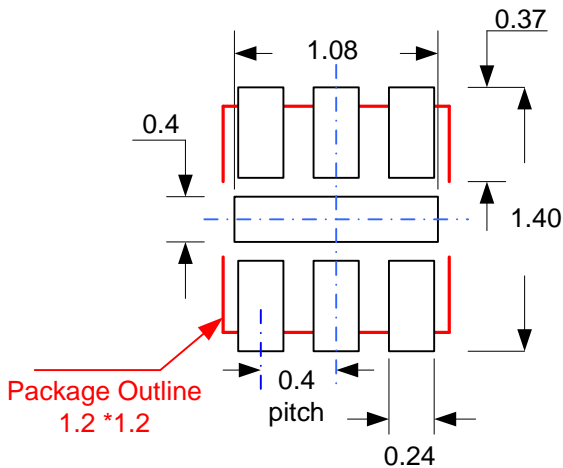
| SYMBOLS | MILLIMETERS | | INCHES | |
|----------------------|-------------|------|------------|--------|
| | MIN | MAX | MIN | MAX |
| A | 0.90 | 1.30 | 0.0354 | 0.0512 |
| A₁ | 0.00 | 0.15 | 0.0000 | 0.0059 |
| b | 0.30 | 0.55 | 0.0118 | 0.0217 |
| D | 2.70 | 3.10 | 0.1063 | 0.1220 |
| E | 1.40 | 1.80 | 0.0551 | 0.0709 |
| e | 1.90 BSC | | 0.0748 BSC | |
| H | 2.60 | 3.00 | 0.1024 | 0.1181 |
| L | 0.37 BSC | | 0.0146 BSC | |
| θ₁ | 0° | 10° | 0° | 10° |
| S₁ | 0.95 BSC | | 0.0374 BSC | |

■ Lead Pattern

Note:

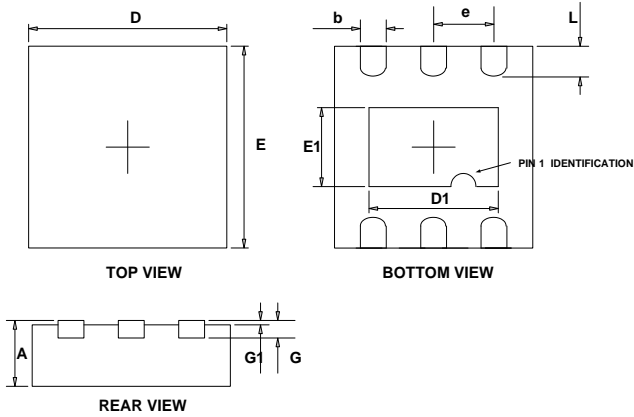
- Lead pattern unit description:
BSC: Basic. Represents theoretical exact dimension or dimension target.
- Dimensions in Millimeters.
- General tolerance $\pm 0.05\text{mm}$ unless otherwise specified.

■ Package Dimension (Contd.)
DFN-6G(1.2x1.2x0.37mm)


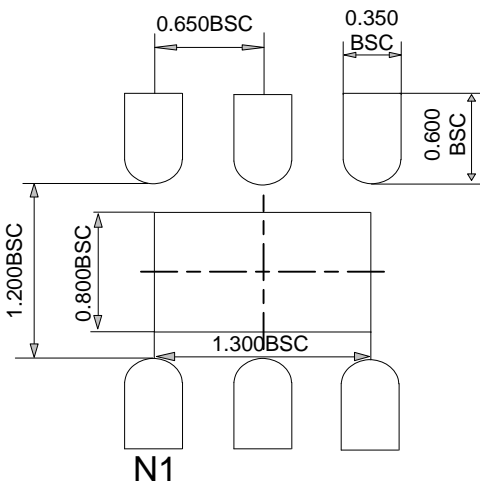
| SYMBOLS | MILLIMETERS | | | INCHES | | |
|-----------|-------------|-------|-------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.340 | 0.370 | 0.400 | 0.013 | 0.015 | 0.016 |
| A1 | 0.000 | 0.020 | 0.050 | 0.000 | 0.001 | 0.002 |
| A2 | 0.100 REF | | | 0.004 REF | | |
| b | 0.130 | 0.180 | 0.230 | 0.005 | 0.007 | 0.009 |
| D | 1.150 | 1.200 | 1.250 | 0.045 | 0.047 | 0.049 |
| E | 1.150 | 1.200 | 1.250 | 0.045 | 0.047 | 0.049 |
| D2 | 0.250 | 0.300 | 0.350 | 0.010 | 0.012 | 0.014 |
| E2 | 0.890 | 0.940 | 0.990 | 0.035 | 0.037 | 0.039 |
| e | 0.300 | 0.400 | 0.500 | 0.012 | 0.016 | 0.020 |
| H | 0.150REF | | | 0.006 REF | | |
| K | 0.110REF | | | 0.004 REF | | |
| K1 | 0.150 | 0.200 | 0.250 | 0.006 | 0.008 | 0.010 |
| L | 0.150 | 0.200 | 0.250 | 0.006 | 0.008 | 0.010 |
| L1 | 0.000 | 0.050 | 0.100 | 0.000 | 0.002 | 0.004 |

■ Lead Pattern


Note:
 1. Dimensions in Millimeters.

■ Package Dimension (Contd.)
DFN-6D(2x2x0.75mm)


| SYMBOLS | MILLIMETERS | | INCHES | |
|-----------|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.700 | 0.800 | 0.028 | 0.031 |
| D | 1.900 | 2.100 | 0.075 | 0.083 |
| E | 1.900 | 2.100 | 0.075 | 0.083 |
| e | 0.650 TYP | | 0.026 TYP | |
| D1 | 1.100 | 1.650 | 0.043 | 0.065 |
| E1 | 0.600 | 1.050 | 0.024 | 0.041 |
| b | 0.180 | 0.350 | 0.007 | 0.014 |
| L | 0.200 | 0.450 | 0.008 | 0.018 |
| G | 0.178 | 0.228 | 0.007 | 0.009 |
| G1 | 0.000 | 0.050 | 0.000 | 0.002 |

■ Lead Pattern

Note:

1. Dimensions in Millimeters.
2. General tolerance $\pm 0.05\text{mm}$ unless otherwise specified.



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Life Support Policy:

These products of AME, Inc. are not authorized for use as critical components in life-support devices or systems, without the express written approval of the president of AME, Inc.

AME, Inc. reserves the right to make changes in the circuitry and specifications of its devices and advises its customers to obtain the latest version of relevant information.

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Document: G006-DS8903-D.01

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